



Capabilities

Copper Clad Laminate (adhesive type)	
Base Film Material	Typical thickness (µm)
PET (Polyester)	75, 100, 125
PEN (Polyethylene Napthalate)	50, 75
PI (Polyimide, Kapton)	50, 75
Copper Foil Type	Typical thickness (µm)
ED (Electrodeposited)	17, 35
RA (Rolled Annealed)	17, 35, 70, 105

Insulating Film		
Type	Thickness (µm)	Accuracy
Screen Printed UV Solder Resist (Covercoat)	15-25	0.3 mm
Liquid Photoimageable Solder Mask (LPISM)	10-25	0.2 mm
Coverlay (PET, PEN, PI)	25, 50	0.3 mm

Stiffener
Material: PET, PEN, PI, FR4, Aluminium
Adhesive Type: PSA, Thermal curing

Surface Finishes		
Type	Thickness	Application
Solder (Roller Tinning)	1 µm ~ 10 µm (Pb/Sn)	Any soldering (not for PET or fine pitch)
Immersion Silver	0.05µm ~ 1.0 µm	SMD
Tin plating	1~10 µm	ZIF connectors
OSP	0.10 - 0.50 µm	SMD, any soldering
ENIG	Ni=4 µm; Au=0.1µm (max)	SMD, ZIF, aluminium wire bonding
Carbon	10 µm	Mechanical Contact pads
Galvanic Hard Gold	Ni 4-8 µm; Au= 1-3µm	Sliding contact, wet environment
HASL	1 µm ~ 10 µm (Pb/Sn)	SMD, ZIF, Any soldering

Parameter	Description
Maximum PCB Size	550 mm x 350 mm
Minimum Tracewidth	150 µm
Minimum Hole Size	0.30 mm
Hole-Hole tolerance	0.05 mm
Hole-Edge Tolerance	0.10 mm
Tooling	Hard Tool, Soft Tool, CNC Routing
Inspection & testing	Dedicated Bare Board Tester, In-circuit Tester